2SA1791

Silicon PNP epitaxial planar type

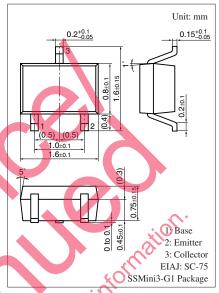
For low-frequency amplification Complementary to 2SC4656

■ Features

- High forward current transfer ratio f_T
- Small collector output capacitance Cob
- SS-Mini type package allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-50	V	
Collector-emitter voltage (Base open)	V _{CEO}	-50	V	
Emitter-base voltage (Collector open)	V_{EBO}	-5	V	
Collector current	I_C	-50	mA	
Collector power dissipation	P_C	125	mW	
Junction temperature	T _j	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



Marking Symbol: AL

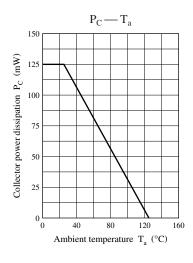
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

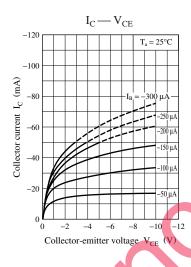
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_{\rm C} = -10 \mu \text{A}, I_{\rm E} = 0$	-50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -1 \text{ mA}, J_{\rm R} = 0$	-50			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = -10$ µA, $I_{\rm C} = 0$	-5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -10 \text{ V}, I_{E} = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -10 \text{ V}, I_{B} = 0$			-100	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$	200		500	_
Collector-emitter saturation voltage	VE(sat)	$I_C = -10 \text{ mA}, I_B = -1 \text{ mA}$		- 0.1	- 0.3	V
Transition frequency	f_{T}	$V_{CB} = -10 \text{ V}, I_E = 2 \text{ mA}, f = 200 \text{ MHz}$		250		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		1.5		pF
(Common base, input open circuited)						

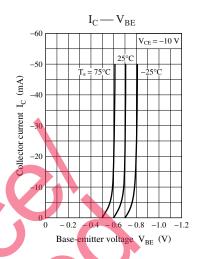
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

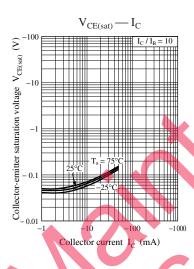
2. *: Rank classification

Rank	Q	R
h_{FE}	200 to 400	250 to 500

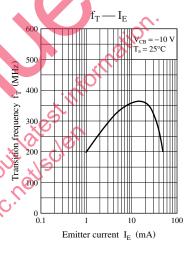


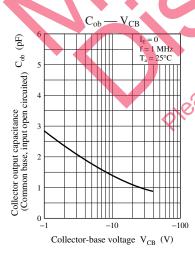












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